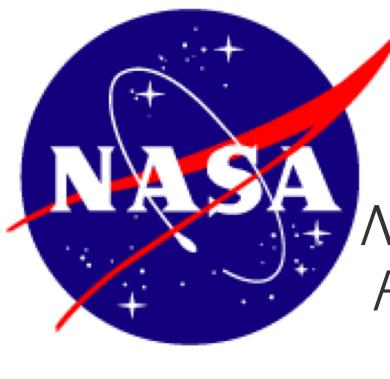
# The impact of transition edge sensor design on achievable performance uniformity of kilo-pixel arrays



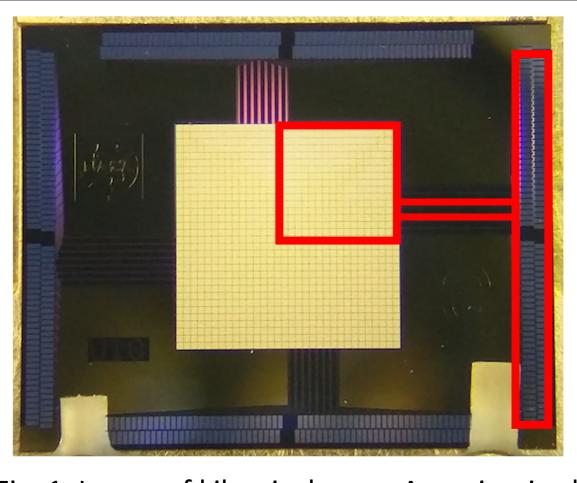
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## Introduction

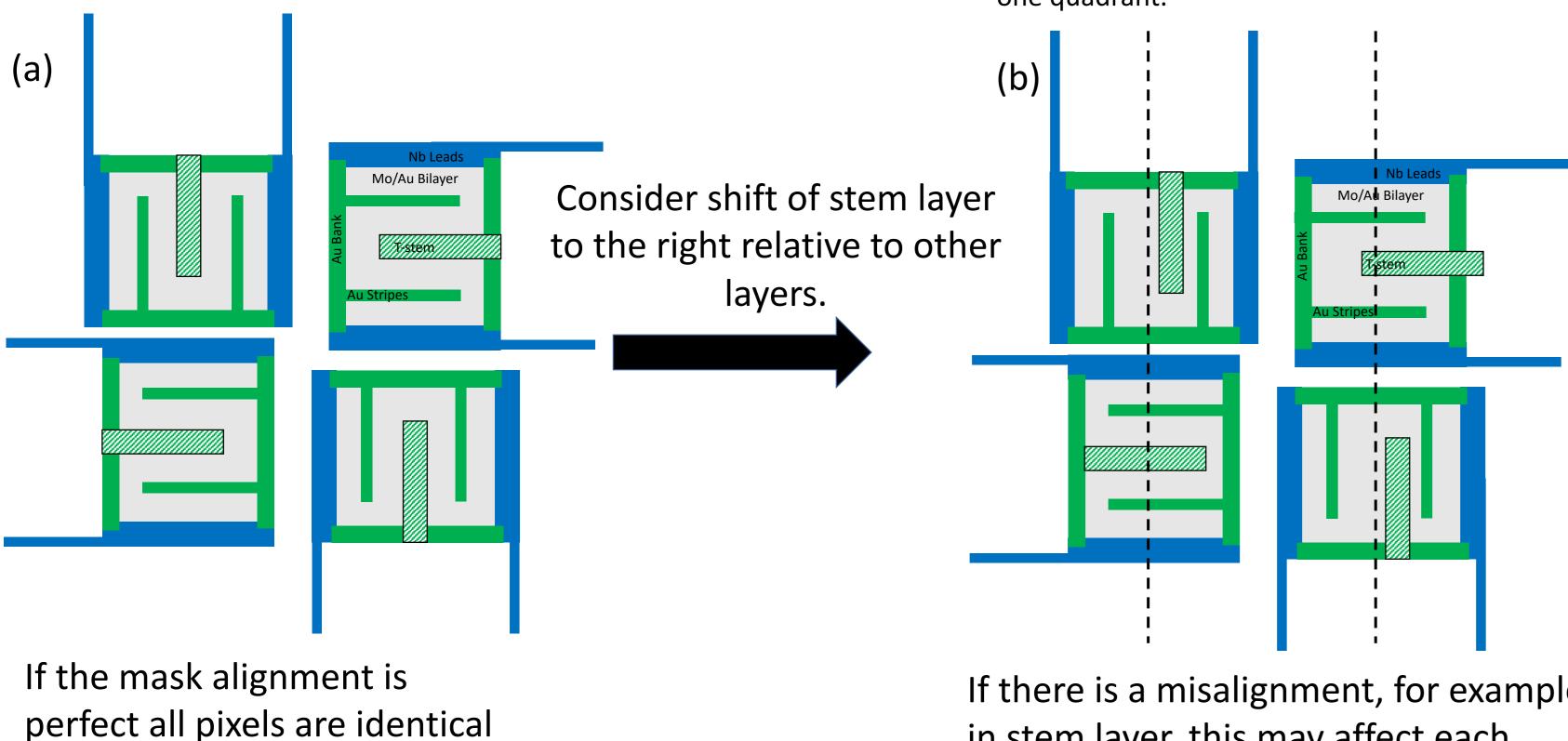
- Future astronomy missions using x-ray transition-edge sensor (TES) microcalorimeters, such as X-IFU on Athena, will require large arrays of 1000s of pixels fabricated on a single wafer. Barret et al., Proc. SPIE, 9905, (2016)
- To wire out so many pixels the current array designs have pixels with different rotational orientations.
- Fabrication is done in multiple layers and so, dependent on method, there is potential for spatial misalignment between layers.
- Because of the variation of orientation of pixels, misalignment may not impact each pixel equally.
- This has the potential to degrade the achievable uniformity of performance across an array.
- How well aligned do different layers need to be?
- How does sensitivity to misalignment depend on choice of pixel design?

# **Current kilo-pixel array design**

- Pixels are wired out in 4 quadrants.
- Each quadrant wires out to a different side of the chip.
- This means there are 4 different rotational orientations of the pixels.
- Each of the center 4 pixels has a different orientation.



one quadrant



If there is a misalignment, for example in stem layer, this may affect each orientation differently.

Fig. 2. Schematic diagram showing the four central TES pixels (absorbers not shown) in our current kilo-pixel array design. TES's have Mo/Au bilayer (light gray) connected with Nb leads (blue), Au banks parallel to the current direction and two Au stripes perpendicular to current direction (solid green), and a large "T-Stem" attachment between the absorber and TES (hashed green). Fig 2(a) shows perfect layer alignment. (b) Shows effect of misalignment of T-stem layer to the right.

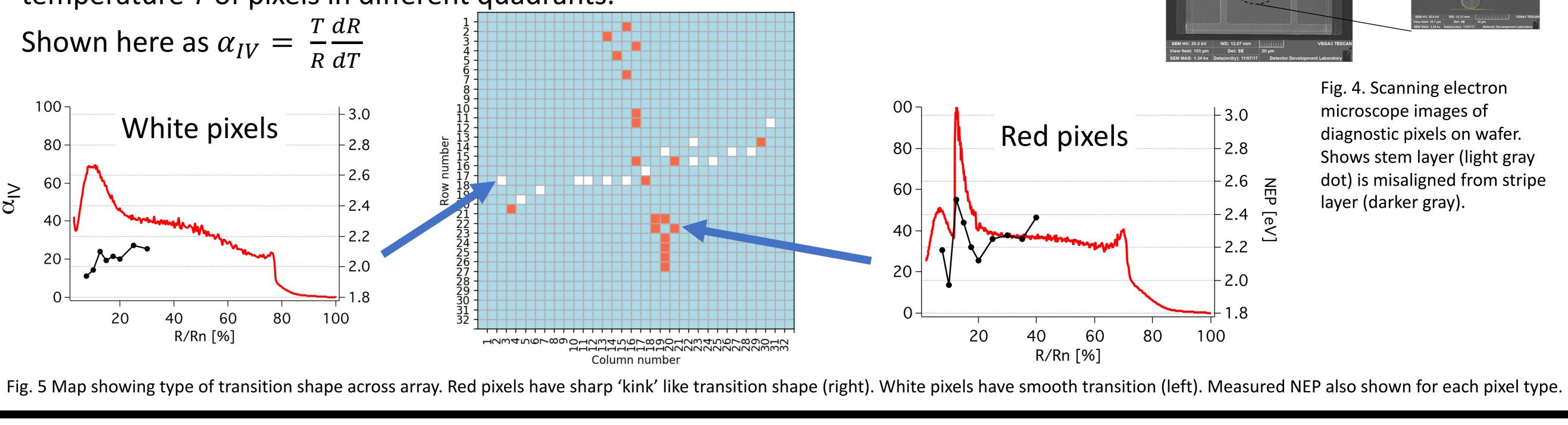
Fig. 1. Image of kilo-pixel array. Array is wired out in four quadrants each with a different rotational orientation. Red box highlights

### **Example of mask misalignment in striped devices** Tc variation

- In misaligned wafer, measured transition properties of a kilo-pixel TES array with normal metal stripes and "T-stem" (Fig 2).
- bilayer.
- quadrants (Fig. 3).
- This is an extreme example but such quadrant dependent  $T_c$  (and transition shape) observed in other striped device arrays.
- Electron microscopy indicated a shift of the stem layer by  $2\mu m$  (Fig. 4). All other layers appear aligned to better than  $1\mu m$ .
- $T_c$  shift agrees with order of magnitude estimates from calculations of  $2\mu m$  change of separation between stem, stripes and banks.

### **Transition shape variation**

Also see a step like change in shape of transition of resistance R with temperature *T* of pixels in different quadrants.



# **No-stripe TES arrays**

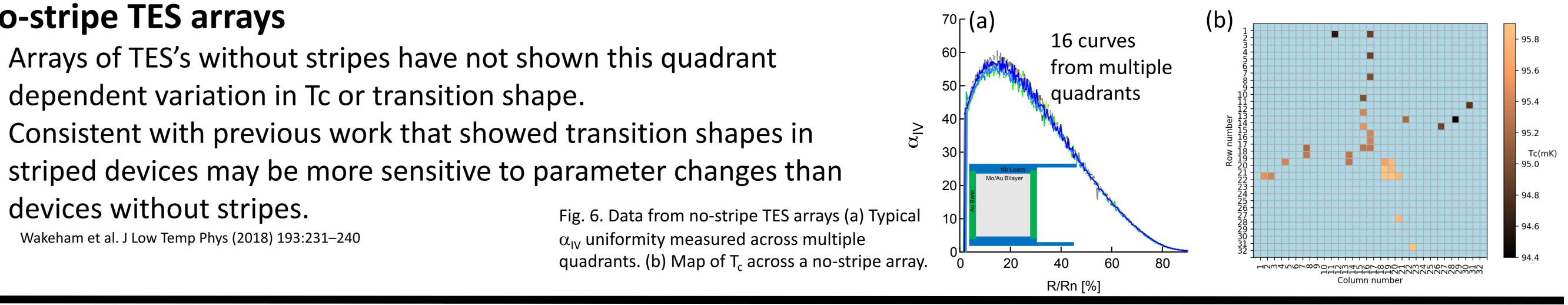
- dependent variation in Tc or transition shape.
- devices without stripes.

Wakeham et al. J Low Temp Phys (2018) 193:231–240

# **Conclusions and Future Work**

Expect a smooth T<sub>c</sub> gradient ~1mK across a chip from small thickness variations in

In this array with stripes we also measured a step change in T<sub>c</sub> ~0.5mK between



Array scale non-uniformity may indicate need for a new fabrication approach in striped TES devices. Kilo-pixel arrays of devices without stripes show smoother, more uniform transition shapes. In the future we will test devices fabricated with systematically varying misalignments of different layers to quantitatively test sensitivity of different TES designs.

